



501.36384C09

~~IPW/S
CC~~

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: FUJISAWA, et al.
Serial No.: 10/611,910
Filed: July 3, 2003
For: METHOD OF MANUFACTURING SEMICONDUCTOR PACKAGE INCLUDING FORMING A RESIN SEALING MEMBER (AS AMENDED)
Group: 2814
Examiner: P. Cao

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

August 9, 2004

Sir:

In response to the Office Action mailed April 8, 2004, please amend the above-identified application as listed in the following, and as set forth on the following pages:

Amendments to the Specification

Amendments to the Claims

Remarks are included following the amendments